# MKP Film Capacitor

**Material Data Sheet**

## Product Class

**Film Capacitor Series**

**B2569x PEC MKP DC**

## Date

18/11/2019

## IMDS ID

NA

## Version

5.02.1a (03/2019)

### Product Part (IMDS: semi component) | Material Class (IMDS: Material) | Material (Classification) | Substance | TMPS(*) [wt-%] | CAS # applicable | typical mass of material [wt-%] | Traces see 1)

#### Active Part

- **Thermoplastic 2A**
  - Polypropylene
  - 100
  - 9003-07-0
  - 52.1
- **Heavy Metals 1C**
  - Zinc
  - 100
  - 7440-66-6
  - 5.4
- **Thermoplastic 2A**
  - PBT
  - 70
  - 20062-94-2
  - 2.2
- **Mineral Materials 3A**
  - Fiber Glass
  - 30
  - 65997-17-3

#### Encapsulation

- **Duromer 2D**
  - Polyurethane
  - 100
  - 67700-43-0
  - 15.6
- **Thermoplastic 2A**
  - PBT
  - 70
  - 20062-94-2
  - 3.4
- **Mineral Materials 3A**
  - Fiber Glass
  - 30
  - 65997-17-3

#### Termination

- **Thermoplastic 2A**
  - PBT
  - 70
  - 20062-94-2
  - 0.8
- **Mineral Materials 3A**
  - Fiber Glass
  - 30
  - 65997-17-3

### Not Part of a Product Class

**Thermoplastic 2A**

**Thermoplastic 2A**

**Thermoplastic 2A**

### Important remarks:

1. The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1% by weight, if not otherwise regulated.

2. This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

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*) others: (not declarable or prohibited substances acc. GADSL)

**) typical mass percentage of substance
RoHS - Exemptions for the Product Class / Product according to Annex III: ( ¥ valid ☐ not valid )

| Exemption 6 (a): | Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35 % lead by weight; |
| Exemption 6 (b): | Lead as an alloying element in aluminium containing up to 0.4 % lead by weight; |
| Exemption 6 (c): | Copper alloy containing up to 4 % lead by weight; |
| Exemption 7 (a): | Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead); |
| Exemption 7 (c)-I: | Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound; |
| Exemption 7 (c)-II: | Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher; |
| Exemption 7 (c)-III: | Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC; |
| Exemption 15: | Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages; |
| Other Exemption than above: | ............................................................ |